



materials



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3D Printing Materials: Innovation, Design and Future Technology

Guest Editor:

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Message from the Guest Editor

Dear Colleagues,

Nowadays, the challenges that the conventional/traditional electronic device industry faces are that the fabrication pathway is complex, there is a high level of generation of heat/harmful chemicals in the deposition process, a high volume of raw material being wasted and also relies on rigid substrates that do not match with the needs of the industry for flexible, bendable electronics. The 3D printing technology is based on the Additive Manufacturing concept and it is no doubt capable of revolutionising the whole system of manufacturing electronic devices including material selection; design and fabrication steps and device configuration and architecture.

This Special Issue will encompass few of the most important aspects of 3D printing, that are shared by all types of the emerging electronic devices, such as: Materials, Innovation, Design and Manufacturing Technologies. We invite both the academia and industry communities to join together and to contribute either by research articles, comments or reviews to this Special Issue.



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Special Issue



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Message from the Editor-in-Chief

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